

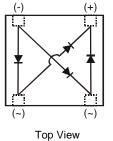


#### **Product Summary**

Ī	V <sub>RRM</sub> (V)	I <sub>0</sub> (A)	V <sub>F MAX</sub> (V) @ +25°C	I <sub>R MAX</sub> (mA) @ +25°С	
	40	2	0.5	0.1	

### Description

Packaged in the compact DFN5060-4 the SBR2A40BLP is designed with low forward voltage and low reverse leakage to meet the needs of LED Lighting applications and wireless charging applications.



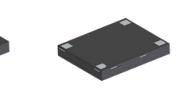
Top View Device Schematic

### **Features and Benefits**

- Low Profile Package, Ideal for Thin Portable Applications
- Low Reverse Leakage Ensuring Greater Stability at Higher Temperatures.
- Low Forward Voltage (V<sub>F</sub>) Minimizes Conduction Losses and Improves Efficiency
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

# Mechanical Data

- Case: V-DFN5060-4
- Case Material: Molded Plastic "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.0715 grams (Approximate)



Bottom View

#### Ordering Information (Note 4)

Part Number	Case	Packaging
SBR2A40BLP-13	V-DFN5060-4	3000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

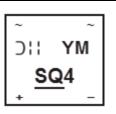
Top View

 See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



SQ4= Product Type Marking Code YM = Date Code Marking Y = Year (ex: Z =2012) M = Month (ex: 9 = September)

Date	Code	Key
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Balo boad hoy												
Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Y		Z		А	E	3	С		D		E
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



#### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	40	V
Average Rectified Output Current	lo	2.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load (Per Diode)	I <sub>FSM</sub>	70	А

### **Thermal Characteristics**

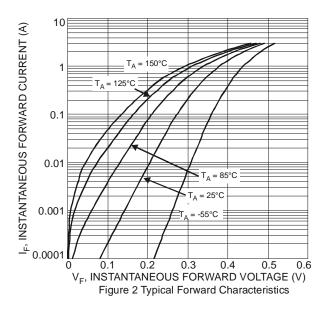
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5)	R <sub>θ</sub> JC	15	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

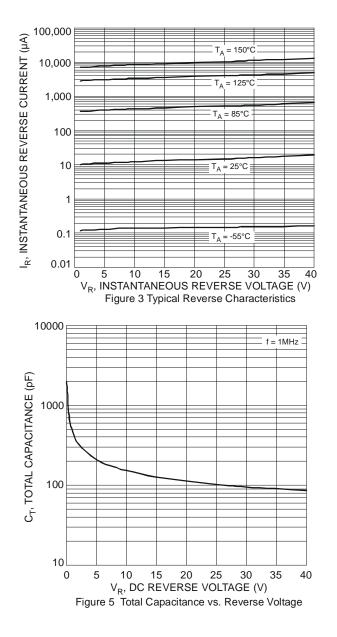
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage (Per Diode)	VF		—	0.50		$I_F = 2.0A, T_J = +25^{\circ}C$
Torward Voltage (Ter Diode)	VF		0.42	0.47	v	$I_F = 2.0A, T_J = +125^{\circ}C$
Reverse Current (Note 6) (Per Diode)	1		—	0.1	mΔ	$V_{R} = 40V, T_{J} = +25^{\circ}C$
Reverse Current (Note 6) (Fer Diode)	I <sub>R</sub>	—	—	10		$V_R = 40V, T_J = +125^{\circ}C$
Total Capacitance	Cτ		90		pF	$V_R = 40V, f = 1.0MHz,$
	υT		90		μr	$T_J = +25^{\circ}C$

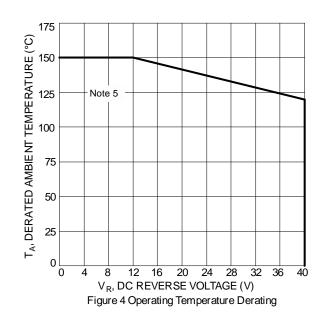
Notes: 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout per http://www.diodes.com. 6. Short duration pulse test used to minimize self-heating effect.

2.5 (M) NOLVENING 2.0  $T_j = 150^{\circ}C$ 1.5 1.0  $d^{\circ}$  0.5 0.5  $I_{F(AV)}$  AVERAGE FORWARD CURRENT (A) Figure 1 Forward Power Dissipation





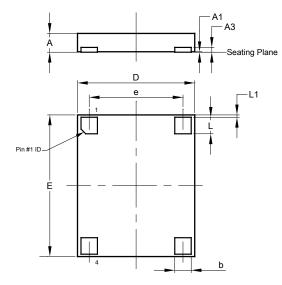






### **Package Outline Dimensions**

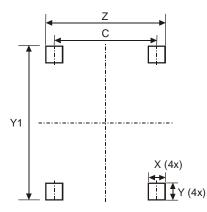
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	V-DFN5060-4							
Dim	Min	Max	Тур					
Α	0.75	0.85	0.80					
A1	0	0.05	0.02					
A3	-	-	0.203					
b	0.65	0.75	0.70					
D	4.95	5.05	5.00					
е	-	-	4.00					
Е	5.95	6.05	6.00					
L	0.65	0.75	0.70					
L1	0.05	0.15	0.10					
All	Dimens	ions in	mm					

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	4.00
Х	0.75
Y	0.95
Y1	6.20
Z	4.75



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